IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants:	Tien-J Bao, et al.	§	Docket No.:	TS02-262CIP (24061.480)
Serial No.:	10/808,801	§		
		§	Examiner:	TBD
Filing Date:	March 25, 2004	§		
		§	Art Unit:	2834
Entitled:	Method for Forming Openings in Low-K Dielectric Layers	§	Conf. No.:	6033

Mail Stop Missing Parts
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

PETITION

Dear Sirs:

In response to the Notice of Omitted Item(s) in a Nonprovisional Application mailed on November 24, 2004 for the above-identified application, the undersigned attorney for applicant hereby provides the following pertinent facts, in accordance with 37 C.F.R. § 1.181:

1. Applicants filed the above-identified application on March 25, 2004 enclosing 32 pages of specification (26 pages of description, 5 pages of claims and 1 page of abstract);

2. The Notice states that Page 21 of the specification was omitted from the application. However, Applicants submit that Page 21 of the specification, a copy of which is enclosed, was included with the original filing on March 25, 2004.

3. Enclosed is a copy of the Return Receipt Postcard date stamped by the U.S. Patent and Trademark Office on March 24, 2004 confirming receipt of 32 pages of specification.

Because the omission of Page 21 occurred through no fault of the Applicant, a refund of the Petition Fee of $130.00 is respectfully requested.

For the reasons set forth above, Applicants respectfully request that this Petition be granted and that the application maintain the filing date of March 25, 2004.

Respectfully submitted,

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